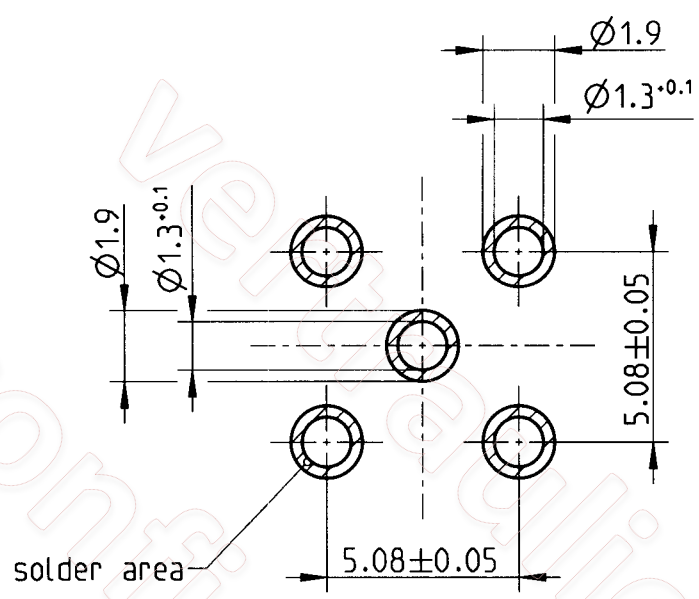


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Leiterplatten-Layout
 PCB layout
 B 30



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

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Formzahl: TCC 06 05 02 A - Einzelteil
 Date: 14. JUN 2006 10:08:58
 Version: 1.1

-METRIC-



ISO-Projektion
 Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 5:1 weight(g): surface(mm ²):			
		material:		Leiterplatten-Layout PCB layout			
		title:					
			date drawn 15.02.2001 A_Nobis check. 20.3.06 appr.	drawing-no.: MB_30 sheet: 1 of: 1			
g00	06-0194	S_Krautenbac	24.03.2006				
f00	04-0709	A_Nobis	22.11.2004			dimensioning incl. finish	
e00	02-0124	A_Nobis	01.10.2003				
d00	01-0425	A_Nobis	06.09.2001				
c00	01-0266	V_Spitzauer	13.06.2001	distribu- tion to:	FE AZ QSM RMT . X		
rev.	change-no	name	date	remarks:			